



# 860 SERIES BGA/LGA

## SPECIFICATIONS:

- Compression Surface Mount BGA/LGA
- A variety of contact technologies can be used for this socket ranging from spring pins to stamped and formed contacts
- Socket Outline : 80mm x 90mm
- Max Package Outline: 45mm x 45mm
- 24 Sockets per MCC Chamber BIB
- 0.8mm and 1.0mm pitch. Consult factory for other pitches

## FEATURES:

- Versatile, low cost socket base
- Passive heat sink or Heat Sink/Heater/Sensor
- Replaceable contact set
- Heater – foil or cartridge as required
- Sensor – RTD in compliant and isolated “button” unless otherwise specified
- Heat Sink – simulations confirm application
- Positive locking lid
- High mechanical advantage lid and latch provides low actuation force for high I/O packages – 12:1



## DESCRIPTION & ORDERING INFORMATION

**860X XXXX - X X - X X**

